

C0603C475K9PAC7411

SMD Comm X5R, Ceramic, 4.7 uF, 10%, 6.3 VDC, X5R, SMD, MLCC, Temperature Stable, Class II, 0603



Click here for the 3D model.

| Dimensions | |
|------------|------------------|
| Chip Size | 0603 |
| L | 1.6mm +/-0.15mm |
| W | 0.8mm +/-0.15mm |
| Т | 0.8mm +/-0.10mm |
| S | 0.7mm MIN |
| В | 0.35mm +/-0.15mm |

| Packaging Specifications | | |
|--------------------------|------------------------|--|
| Packaging | T&R, 330mm, Paper Tape | |
| Packaging Quantity | 15000 | |

| General Information | |
|---------------------|---|
| Series | SMD Comm X5R |
| Style | SMD Chip |
| Description | SMD, MLCC, Temperature Stable, Class II |
| Features | Temperature Stable, Class II |
| RoHS | Yes |
| Termination | Tin |
| Marking | No |
| AEC-Q200 | No |
| Component Weight | 6.5 mg |
| Shelf Life | 78 Weeks |
| MSL | 1 |

| Specifications | |
|--|--|
| Capacitance | 4.7 uF |
| Measurement Condition | 1 kHz 1.0Vrms |
| Capacitance Tolerance | 10% |
| Voltage DC | 6.3 VDC |
| Dielectric Withstanding Voltage | 15.75 VDC |
| Temperature Range | -55/+85°C |
| Temperature Coefficient | X5R |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | 15%, 1kHz 0.5Vrms |
| Dissipation Factor | 10% 1 kHz 1.0Vrms |
| Aging Rate | 5% Loss/Decade Hour: Referee Time is 48 Hours |
| Insulation Resistance | 21.3 MOhms |

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